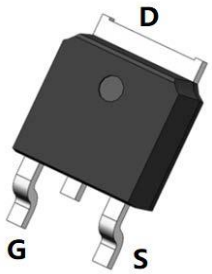
Features

- 20V, 40A

  $R_{DS(ON)}$ Typ = 6.2mΩ @ V_{GS} = 4.5V

  $R_{DS(ON)}$ Typ = 9.1mΩ @ V_{GS} = 2.5V
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!



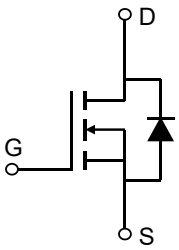
TO-252-3L

Application

- Load Switch
- PWM Application
- Power Management



Pin Assignment



Schematic Diagram

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		20	V
V_{GS}	Gate-to-Source Voltage		±12	V
I_D	Continuous Drain Current	T_C = 25°C	40	A
		T_C = 100°C	24	A
I_{DM}	Pulsed Drain Current (1)		160	A
E_{AS}	Single Pulsed Avalanche Energy (2)		90	mJ
P_D	Power Dissipation	T_C = 25°C	27	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		4.6	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	I_D = 250μA, V_{GS} = 0V	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 20V, V_{GS} = 0V	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	V_{DS} = 0V, V_{GS} = ±12V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA	0.4	0.65	1	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance(3)	V_{GS} = 4.5V, I_D = 20A	-	6.2	9.5	mΩ
		V_{GS} = 2.5V, I_D = 10A	-	9.1	13.5	mΩ
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{GS} = 0V, V_{DS} = 10V, f = 1MHz	-	1055	-	pF
C_{oss}	Output Capacitance		-	160	-	pF
C_{rss}	Reverse Transfer Capacitance		-	140	-	pF
Q_g	Total Gate Charge	V_{GS} = 0 to 4.5V V_{DS} = 10V, I_D = 15A	-	13	-	nC
Q_{gs}	Gate Source Charge		-	2.5	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	3.5	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime	V_{GS} = 4.5V, V_{DD} = 10V I_D= 15A, R_{GEN} = 3Ω	-	8	-	ns
t_r	Turn-On Rise Time		-	19	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	30	-	ns
t_f	Turn-Off Fall Time		-	11	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	40	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	160	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS} = 0V, I_S = 15A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I_F = 15A, di/dt = 100A/us	-	7.5	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	1.5	-	nC

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. E_{AS} condition: Starting T_J=25°C, V_{DD}=10V, V_G=10V, R_G=25ohm, L=0.5mH, I_{AS}=19A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Typical Performance Characteristics

Figure 1: Output Characteristics

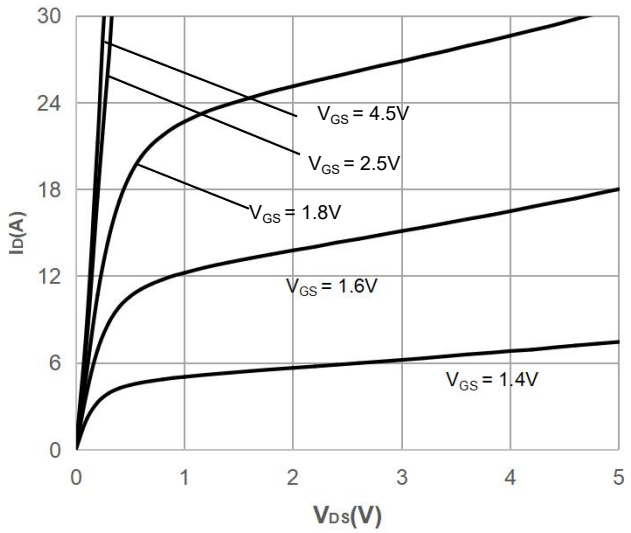


Figure 2: Typical Transfer Characteristics

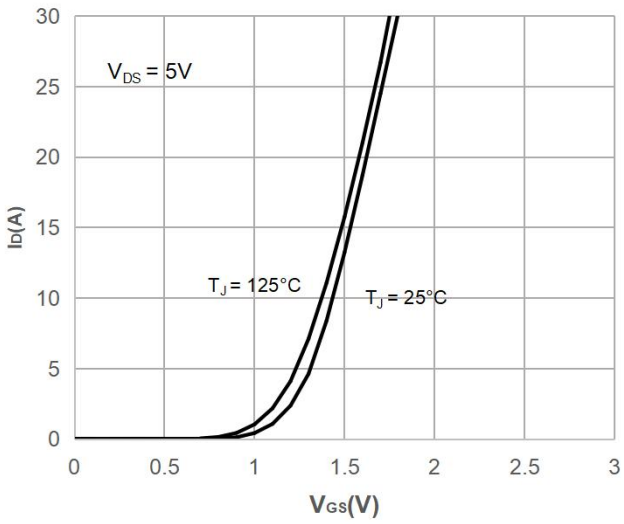


Figure 3: On-resistance vs. Drain Current

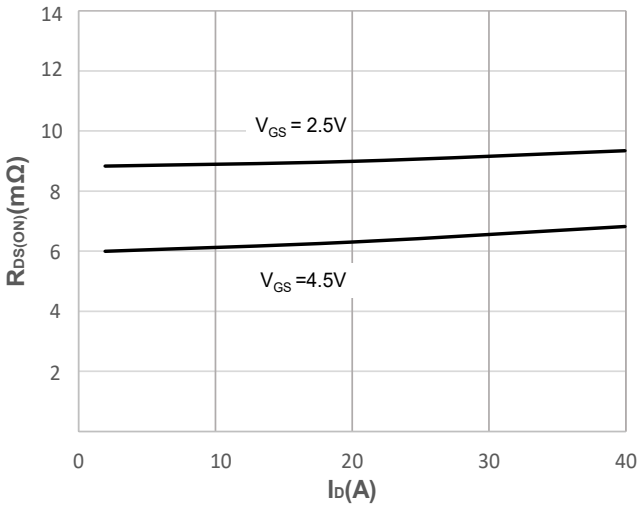


Figure 4: Body Diode Characteristics

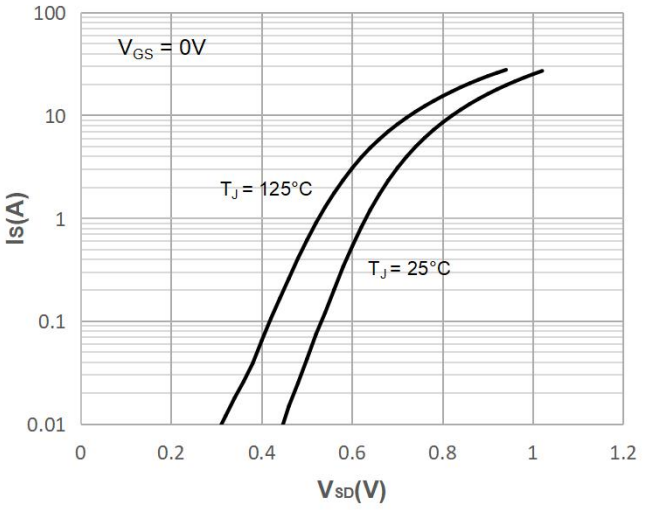


Figure 5: Gate Charge Characteristics

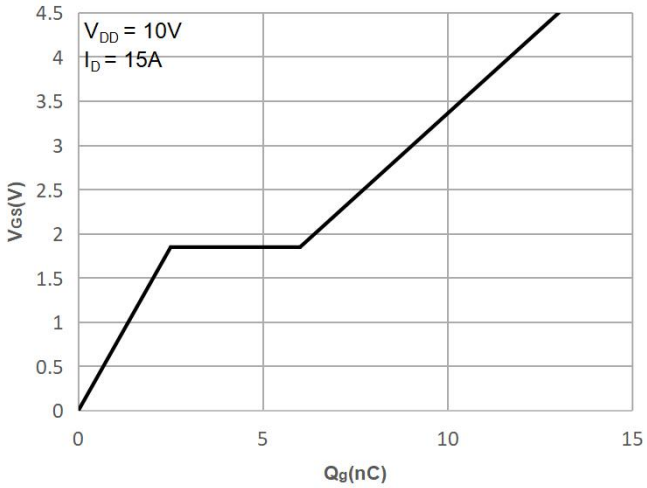
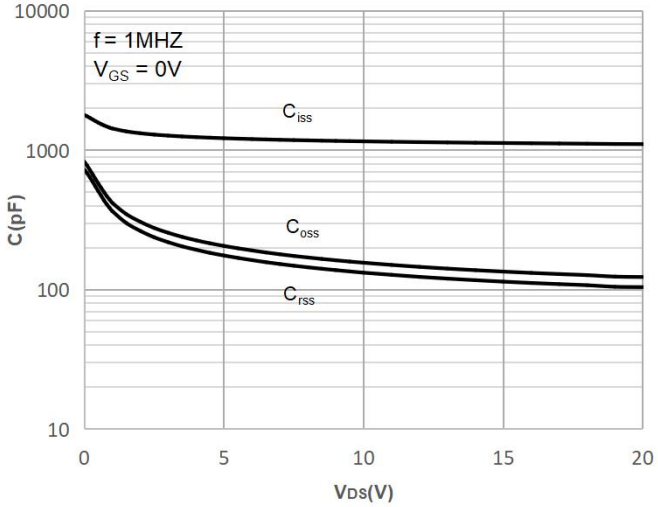


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

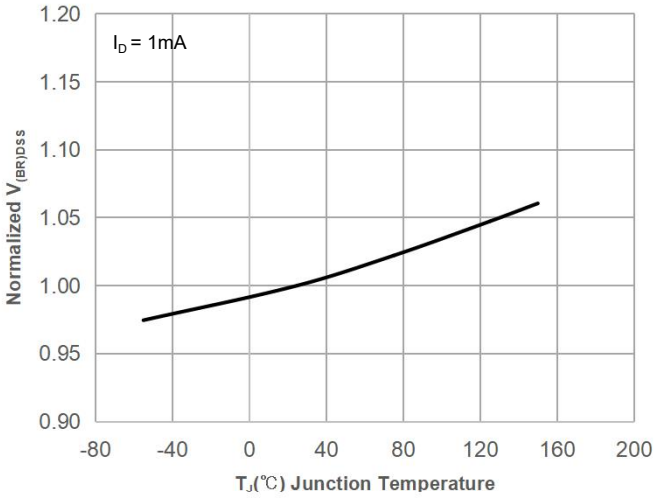


Figure 8: Normalized on Resistance vs. Junction Temperature

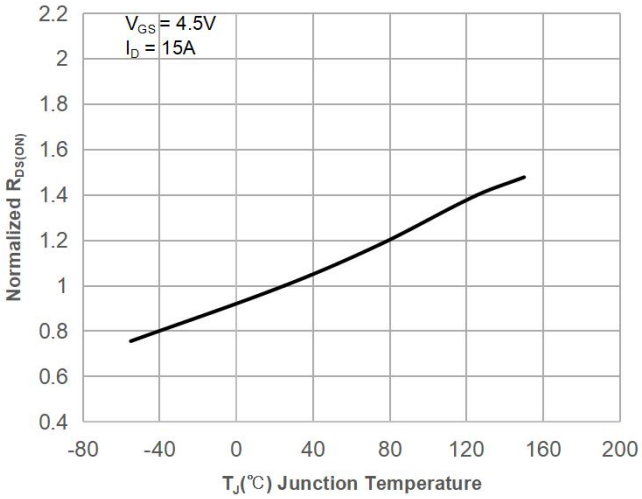


Figure 9: Maximum Safe Operating Area

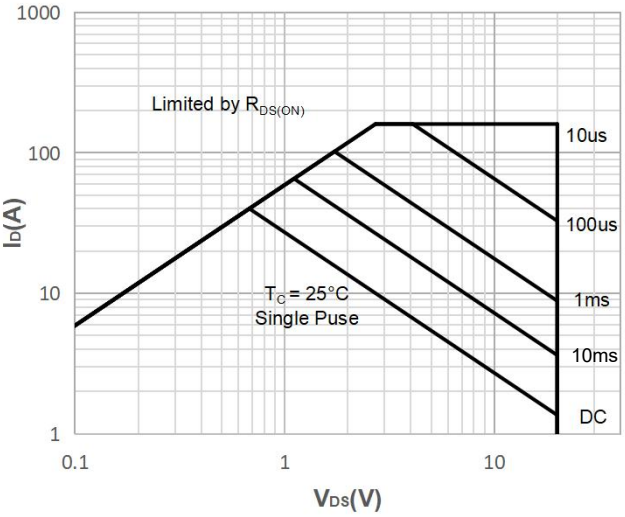


Figure 10: Maximum Continuous Drian Current vs. Case Temperature

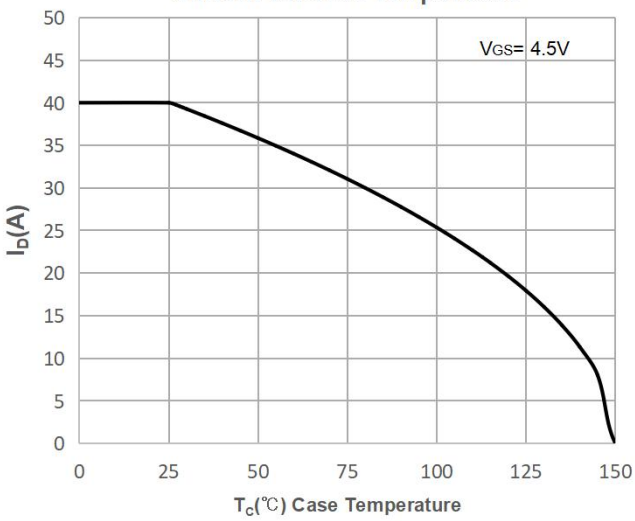


Figure 11: Normalized Maximum Transient Thermal Impedance

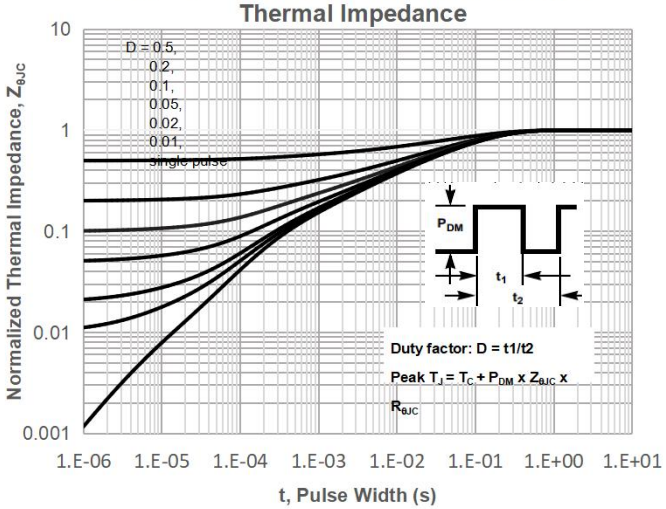
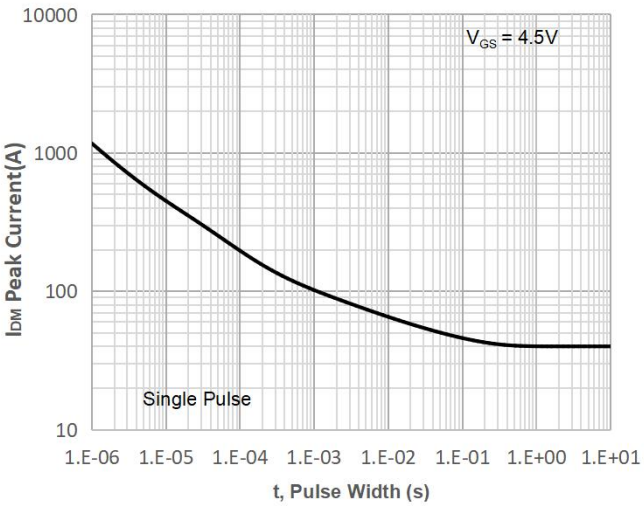


Figure 12: Peak Current Capacity



Test Circuit

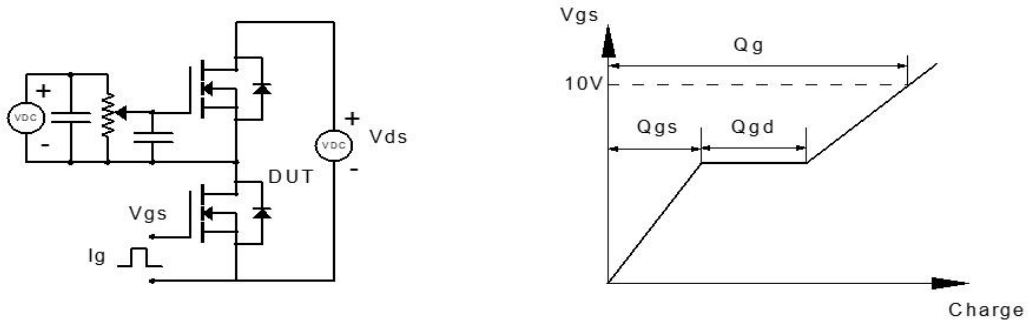


Figure 1: Gate Charge Test Circuit & Waveform

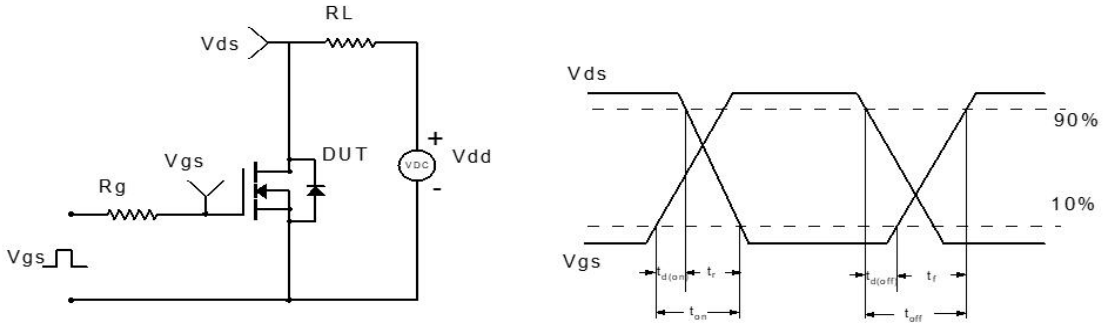


Figure 2: Resistive Switching Test Circuit & Waveform

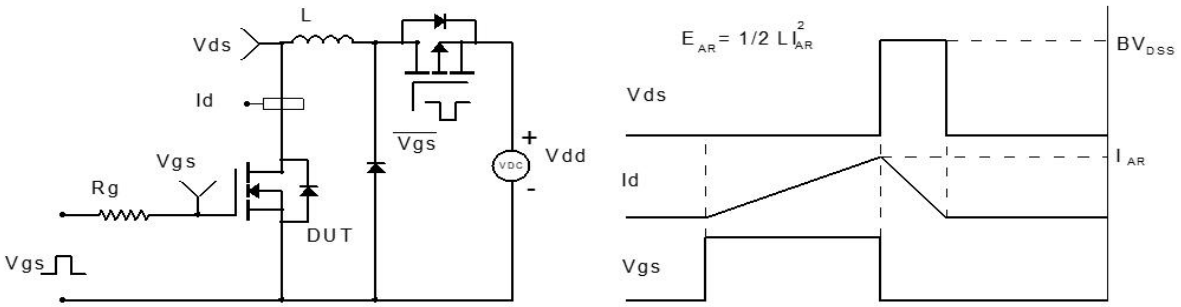


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

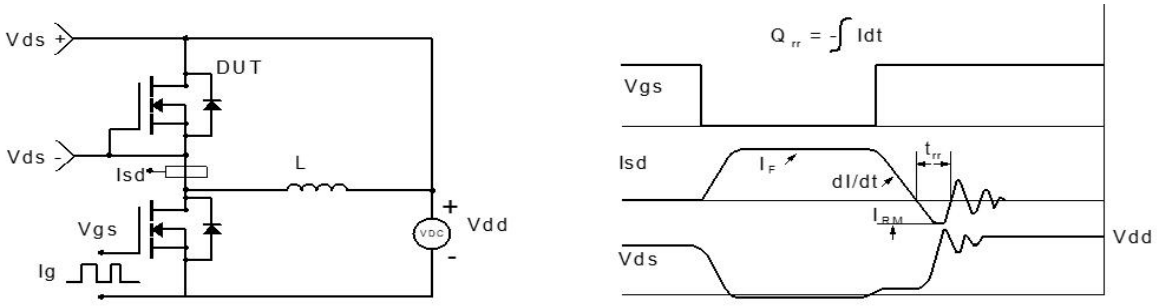
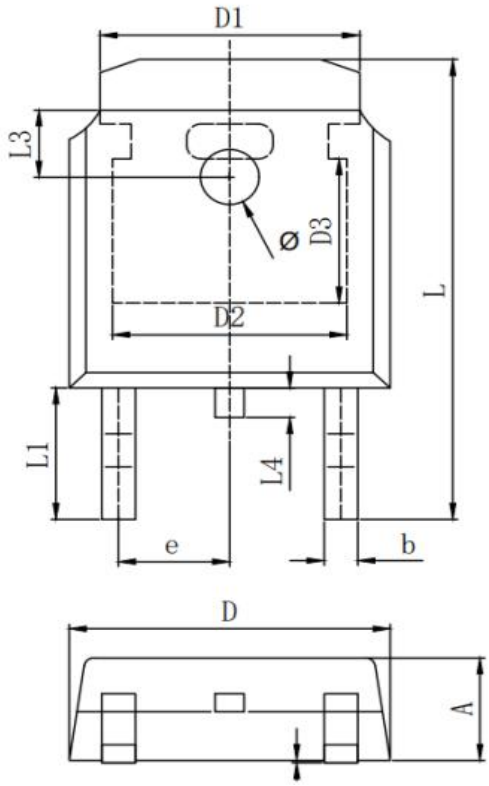
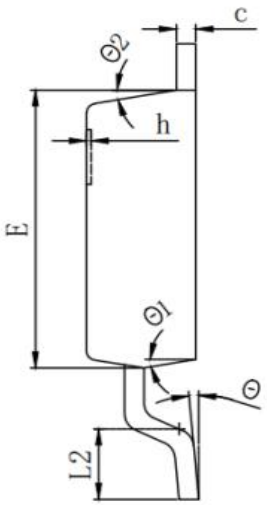


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(TO-252-3L)





SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c(电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
Φ	1.100	1.200	1.300
θ	0°		8°
θ1	9° TYP		
θ2	9° TYP		